



Computational Power is Core US Competitive Advantage

Across the numerous metrics for evaluating AI competitiveness, the United States enjoys the largest, order-of-magnitude advantage in AI computational power through its leadership in not only GPUs (i.e., NVIDIA), but the entire microchip supply chain and ecosystem including software, design and cluster performance. Against this backdrop, the US government's decision on Dec 8th to permit commercial sale to China of the most powerful chip in the older generation Hooper architecture (H200) has been viewed by many as a strategic misstep that has notably diluted US AI competitiveness and national security. The newest generation NVIDIA Blackwell chips (B300, B30) are still subject to US export restrictions.

Metrics for evaluating US-China AI competitiveness



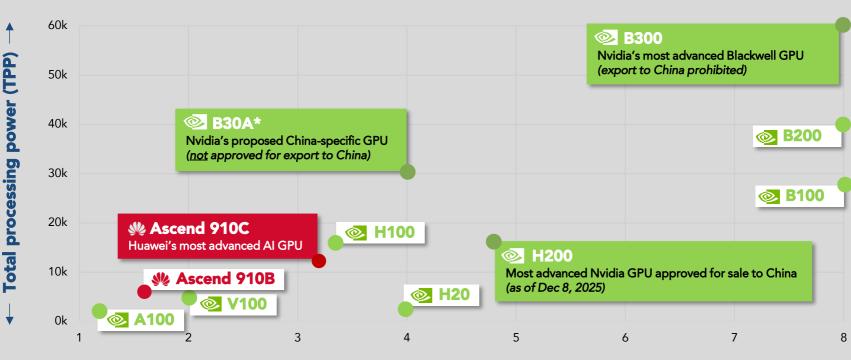
with integration across a plethora of business applications

Nvidia vs. Huawei Al Chip Capabilities

The US Government has explicit restrictions on the sale of both NVIDIA's most advanced Blackwell generation B300 AI GPU to China, as well as the less powerful NVIDIA B30A **GPU** (often dubbed "half a B300), which NVIDIA customized with China in mind. However, on Dec 8, 2025, the US Government did approve exports of NVIDIA's most advanced Hopper generation H200 chip, the most advanced US AI GPU approved for commercial use in China to date. While not nearly as high performing as the B300, NVIDIA's H200 is generally more capable than Huawei's most advanced chip, the **Ascend 910C**, and nearly on par with NVIDIA's B30A GPU.

60k

Nvidia & Huawei AI chip capabilities



Memory bandwidth (TB/s)

S. Korea:

63%

Japan: 6%

Taiwan: 6%

Metric H20 H200 **B30A Nvidia GPU** Nvidia GPU under Nvidia's customized

Comparison of Nvidia's Al GPUs for China



Nvidia's most

NVIDIA

Background	Description	prior US export compliance standard	approved by US gov't on Dec 8	Al GPU for China	advanced AI GPU
	Generation	Hopper	Hopper	Blackwell	Blackwell
	Approved for export to China	Yes	Yes	No	No
Processing Power	Al processor die	1 die	1 die	1 die	2 dies
	Total processing performance (TPP)	2.4k	15.8k	30k	60k
	GPU thermal design power (TDP)	350W	700W	700W	1400W
Memory	Memory Bandwidth	4 TB/s	4.8 TB/s	4 TB/s	8 TB/s
	Memory Capacity	96 GB HBM3E	141 GB HBM3E	144 GB HBM3E	288 GB HBM3E
	High-bandwidth memory stacks	6 stacks	6 stacks	4 stacks	8 stacks
Other	Estimated retail cost	\$10-13k	~\$30k (25% surcharge paid to US gov't)	\$20-25K	\$50-55K
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US-Aliç	gned Blod	: Dominat	tes Globa	I	

While China has made enormous strides in numerous critical technologies, the US-aligned bloc (US, Europe, Japan, SK, Taiwan) enjoys enormous advantages in semiconductor software, design, equipment and high-end manufacturing. Globally coordinated restrictions on the sharing of microchip software, design and equipment have become a centerpiece in US-China policy.

Semiconductor Supply Chain

Semiconductor industry value added, by activity and region (2024) IP / EDA software design tools Logic design Memory design Taiwan: 8% US: Europe: 7% 22% **Europe:** China: 6% 29% US: US: China: 6%

Japan: 3%

The global semiconductor supply chain is highly complex and regionally specialized.



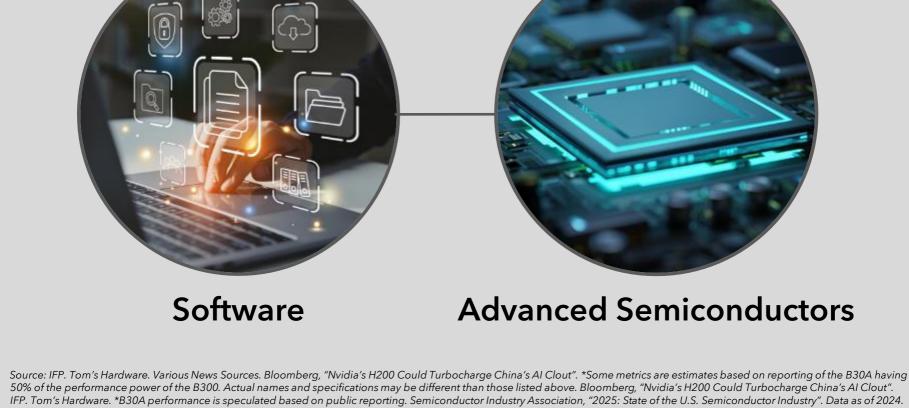
Japan: 2%

66%

73%



over the last decade, well establishing themselves as the world's second most formidable global technology power. However, more so than most other areas, China notably lags US and western innovation in two fundamental, core technology arenas: software and advanced microprocessors.



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